

QUADRUPLE BUS TRANSCEIVERS

FEATURES

- Two-Way Asynchronous Communication Between Data Buses
- PNP Inputs Reduce D-C Loading
- Hysteresis (Typically 400 mV) at Inputs Improves Noise Margin

SN54LS243 . . . J OR W PACKAGE SN74LS243 . . . D, N, OR NS PACKAGE (TOP VIEW)

GAB [1	<u></u> 14	□ v _{cc}
NC [2	13	GBA
A1	3	12	NC
A2 🗌	4	11	☐ B1
A3 🗌	5	10	☐ B2
A4 🗌	6	9	☐ B3
GND [7	8	☐ B4

FUNCTION TABLE (EACH TRANSCEIVER)

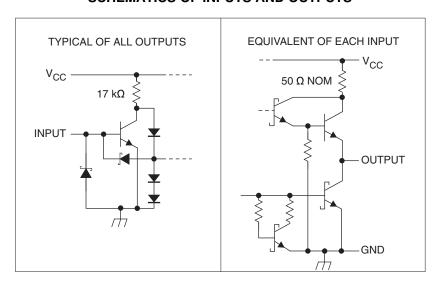
INP	UTS	Chlord C042
GAB	GBA	SNxxLS243
L	L	A to B
Н	Н	B to A
Н	L	Isolation
L	Н	Latch A and B (A = B)

DESCRIPTION

These four-data-line transceivers are designed for asynchronous two-way communications between data buses. SN74LS243 can be used to drive terminated lines down to $133~\Omega$.

SN54LS243 is characterized for operation over the full military temperature range of -55°C to 125°C. SN74LS243 is characterized for operation from 0°C to 70°C.

SCHEMATICS OF INPUTS AND OUTPUTS

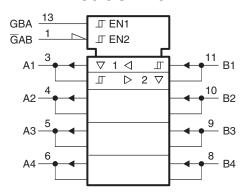




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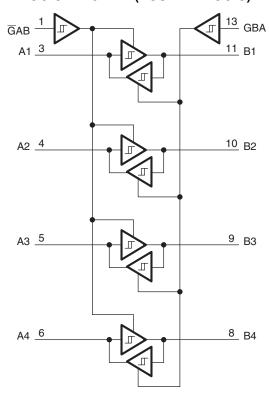


LOGIC SYMBOL



A. These symbols are in accordance with ANSI/EEE Std. 91-1984 and IEC Publication 617-12.

LOGIC DIAGRAM (POSITIVE LOGIC)





ABSOLUTE MAXIMUM RATINGS(1)

				MIN	MAX	UNIT	
V _{CC}	Supply voltage ⁽²⁾	Supply voltage (2)				V	
V _{IN}	Input voltage			7	V		
	OFF-state output voltage	OFF-state output voltage				V	
_	Out and the office of the terror and the out of the out	SN54LS243		- 55	125	00	
IA	Operating free-air temperature range	SN74LS243		0	70	°C	
T _{stg}	Storage temperature range			-65	150	°C	

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		SNS	SN54LS243			SN74LS243			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V_{CC}	Supply voltage ⁽¹⁾	4.5	5	5.5	4.75	5	5.25	V	
V _{IH}	High-level input voltage	2			2			V	
V_{IL}	Low-level input voltage			0.7			8.0	V	
I _{OH}	High-level output voltage			-12			-15	mA	
I _{OL}	Low-level output voltage			12			24	mA	
T _A	Operating free-air temperature	-55		125	0		70	°C	

⁽¹⁾ Voltage values are with respect to network ground terminal.

⁽²⁾ Voltage values are with respect to network ground terminal.



ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	DADAMETED	_	TEST CONDITIONS ⁽¹⁾			4LS243		SN	UNIT		
	PARAMETER		EST CONDITI	ONS	MIN	TYP ⁽²⁾	MAX	MIN	TYP ⁽²⁾	MAX	UNII
V_{IK}	A or B	$V_{CC} = MIN,$	$I_{I} = -18 \text{ mA}$				-1.5			-1.5	V
Hyster	esis (V _{T+} - V _{T-})	$V_{CC} = MIN,$			0.2	0.4		0.2	0.4		٧
.,		V MINI	V 2V	V _{IL} = MAX, I _{OH} = -3 mA	2.4	3.1		2.4	3.1		V
V _{OH}		V _{CC} = MIN,	ν _{IH} = 2 ν,	$V_{IL} = 0.5 \text{ V},$ $I_{OH} = \text{MAX}$	2			2			
V	V _{CC} =		$V_{IH} = 2 V$,	$I_{OL} = 12 \text{ mA}$		0.25	0.4		0.25	0.4	٧
V _{OL}		$V_{IL} = MAX$		I _{OL} = 24 mA					0.35	0.5	V
I _{OZH}		$V_{CC} = MIN,$ $V_{IL} = MAX,$	$V_{IH} = 2 V$,	$V_0 = 2.7 \text{ V}$			40			40	μΑ
I _{OZL}		$V_{CC} = MIN,$ $V_{IL} = MAX,$	$V_{IH} = 2 V$,	$V_O = 0.4 \text{ V}$			-200			-200	μΑ
ı	A or B	V MAX	$V_{CC} = MAX$, $V_{I} = 5.5 \text{ V}$				0.1			0.1	mA
l _l	GAB or GBA	V _{CC} = IVIAX,		$V_I = 7 V$			0.1			0.1	ША
I _{IH}		$V_{CC} = MAX$,					20			20	μΑ
	A inputs	V _{CC} = MAX, GAB and GB					-0.2			-0.2	
I _{IL}	B inputs		$V_{CC} = MAX$, $V_I = 0.4 V$, GAB and GBA at 4.5 V				-0.2			-0.2	mA
	GAB or GBA	$V_{CC} = MAX$,	V _I = 0.4 V,				-0.2			-0.2	
Ios	1	$V_{CC} = MAX$			-40		-225	-40		-225	mA
	Outputs high					22	38		22	38	
I _{CC}	Outputs low	$V_{CC} = MAX,$	Outputs open			29	50		29	50	mA
.00	All outputs disabled	(3)	Catpato opon	Juipuis Opeii,		32	54		32	54	, ۱

⁽¹⁾ For conditions shown as MIN or MAX, use the appropriate value specified under "recommended operating conditions."

SWITCHING CHARACTERISTICS

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CO	SN5		SN	UNIT				
PARAMETER	1551 60	SNOTTIONS	MIN	TYP	MAX	MIN	TYP	MAX	ONII
t _{PLH}	$R_{L} = 667 \ \Omega,$ $R_{L} = 667 \ \Omega,$			9	14		12	18	ns
t _{PHL}		C _L = 45 pF		12	18		12	18	ns
t _{PZL}				20	30		20	30	ns
t _{PZH}				15	23		15	23	ns
t _{PLZ}		$C_1 = 5 pF$		10	20		10	20	ns
t _{PHZ}		O _L = 3 μι		15	25		15	25	ns

Submit Documentation Feedback

All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. I_{CC} is measured with transceivers eabled in one direction only, or with all transceivers disabled.





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
8002002CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8002002CA SNJ54LS243J	Samples
8002002DA	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8002002DA SNJ54LS243W	Samples
SN54LS243J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54LS243J	Samples
SN74LS243D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS243	Samples
SN74LS243DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS243	Samples
SN74LS243N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS243N	Samples
SN74LS243NE4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS243N	Samples
SNJ54LS243J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8002002CA SNJ54LS243J	Samples
SNJ54LS243W	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8002002DA SNJ54LS243W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

TEXAS INSTRUMENTS

6-Feb-2020

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS243, SN74LS243:

Catalog: SN74LS243

Military: SN54LS243

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 26-Jan-2013

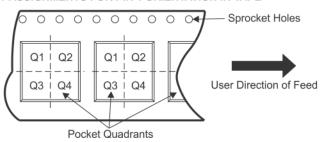
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS243DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 26-Jan-2013



*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
I	SN74LS243DR	SOIC	D	14	2500	367.0	367.0	38.0	

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a certain is using glass int.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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